

Flip Chip - P/N/P ZENER DIODE SPECIFICATION

PART NO.	Document ID.	DATE	REV.
16HBPA009UL	CS-1Z01601	2017/06/13	C

1. Scope :

1.1. This specification is for Flip Chip - P/N/P zener with bi-directional structure

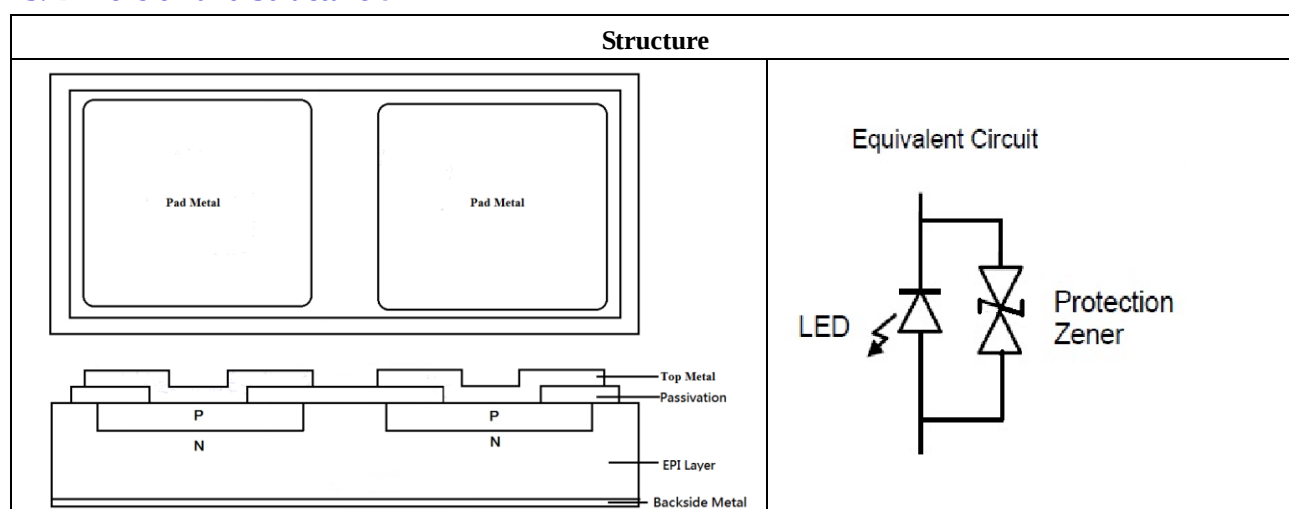
2. Application :

2.1. Paralleled the LED

2.2. Dual pad metal

2.3. Two way Zener diode protection

3. Dimension and Structure :



Dimension		
Item	Characteristics	
Chip Form Die Size	400*160 ± 10.7 um	15.75*6.3 ± 0.42 mil
Pad Size	120 ± 5.0 um	4.72 ± 0.20 mil
Chip Thickness	101.6 ± 12.7 um	4.00 ± 0.50 mil
Passivation	390*150 ± 5.0 um	15.35*5.91 ± 0.20 mil
Top Metallization	SnAu	
Backside Metal	Al	

4. Electrical characteristics (Ta = 25 °C) :

Item	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Zener Voltage	Vz1(Forward)	7.0		10.0	V	Izf1=5mA
	Vz2(Forward)	7.0		10.0	V	Izf2=10uA
	Vz1(Reverse)	7.0		10.0	V	Izr1=5mA
	Vz2(Reverse)	7.0		10.0	V	Izr2=10uA
Leakage Current	Idf			0.5 500	uA nA	V=5V
	Idr			0.5 500	uA nA	V=5V

5. Absolut maximum ratings (Ta = 25 °C) :

Item (Symbol)	Maximum Rating	Unit
Junction Temperature (Tj)	150	C

